

Chairmen's Welcome Message

In the next decades, power electronic system development will be driven by energy saving systems, intelligent energy management, power quality, system miniaturization and high reliability. Monolithic and hybrid system integration will include advanced device concepts including wide bandgap devices, new packaging technologies and the overall integration of actuators/drives (mechatronic integration).

CIPS is consequently focused on the following main aspects:

- assembly and interconnect technology for power electronic devices and converters
- integration of hybrid systems and mechatronic systems with high power density
- systems' and components' operational behaviour and reliability

Basic technologies for integrated power electronic systems as well as upcoming new important applications will be presented in interdisciplinary invited papers.

In 2022 the successful story of CIPS will continue as the conference focus is today more important than ever - increasing functionality, energy efficiency and system reliability while decreasing cost.

We are pleased to welcome all engineers coming from industry and academia engaged in power electronics-related

- system development
- component development
- reliability engineering
- research

to share their research and technical achievements joining CIPS 2022.

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Topic Chairs

Components to be integrated & Mechatronic systems and their applications

Cyril Buttay, Université de Lyon Laboratoire Ampere CNRS UMR 5005, France
Regine Mallwitz, Technische Universität Braunschweig, Germany

Reliability

Norbert Seliger, FH Rosenheim, Germany
Eckhard Wolfgang, ECPE e.V., Germany

General aspects of packaging & Power packages and modules

Guo-Quan Lu, Virginia Techm, USA
Jürgen Wilde, Albert-Ludwigs-Universität Freiburg, Germany

Clean switching, electromagnetic compatibility (EMC)

Reinhold Bayerer, Infineon Technologies AG, Germany
Jean-Luc Schanen, Grenoble Electrical Engineering Laboratory, France

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